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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	84
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-PQFP (20x14)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128eqc100-10nc

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table 2. MAX	7000S Device I	Features -				
Feature	EPM7032S	EPM7064S	EPM7128S	EPM7160S	EPM7192S	EPM7256S
Usable gates	600	1,250	2,500	3,200	3,750	5,000
Macrocells	32	64	128	160	192	256
Logic array blocks	2	4	8	10	12	16
Maximum user I/O pins	36	68	100	104	124	164
t _{PD} (ns)	5	5	6	6	7.5	7.5
t _{SU} (ns)	2.9	2.9	3.4	3.4	4.1	3.9
t _{FSU} (ns)	2.5	2.5	2.5	2.5	3	3
t _{CO1} (ns)	3.2	3.2	4	3.9	4.7	4.7
f _{CNT} (MHz)	175.4	175.4	147.1	149.3	125.0	128.2

...and More Features

- Open-drain output option in MAX 7000S devices
- Programmable macrocell flipflops with individual clear, preset, clock, and clock enable controls
- Programmable power-saving mode for a reduction of over 50% in each macrocell
- Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
- 44 to 208 pins available in plastic J-lead chip carrier (PLCC), ceramic pin-grid array (PGA), plastic quad flat pack (PQFP), power quad flat pack (RQFP), and 1.0-mm thin quad flat pack (TQFP) packages
- Programmable security bit for protection of proprietary designs
- 3.3-V or 5.0-V operation
 - MultiVoltTM I/O interface operation, allowing devices to interface with 3.3-V or 5.0-V devices (MultiVolt I/O operation is not available in 44-pin packages)
 - Pin compatible with low-voltage MAX 7000A and MAX 7000B devices
- Enhanced features available in MAX 7000E and MAX 7000S devices
 - Six pin- or logic-driven output enable signals
 - Two global clock signals with optional inversion
 - Enhanced interconnect resources for improved routability
 - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
 - Programmable output slew-rate control
- Software design support and automatic place-and-route provided by Altera's development system for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations

- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
 - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
 - The BitBlasterTM serial download cable, ByteBlasterMVTM parallel port download cable, and MasterBlasterTM serial/universal serial bus (USB) download cable program MAX 7000S devices

General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2.* See Table 3 for available speed grades.

Device	Speed Grade												
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20			
EPM7032		✓	✓		✓		✓	✓	✓				
EPM7032S	✓	✓	✓		✓								
EPM7064		✓	✓		~		✓	✓					
EPM7064S	✓	✓	✓		~								
EPM7096			✓		~		✓	✓					
EPM7128E			✓	✓	~		✓	✓		✓			
EPM7128S		✓	✓		✓			✓					
EPM7160E				✓	✓		✓	✓		✓			
EPM7160S		✓	✓		~			✓					
EPM7192E						✓	✓	✓		✓			
EPM7192S			✓		✓			✓					
EPM7256E						✓	✓	✓		✓			
EPM7256S			✓		✓			✓					

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Table 4. MAX 7000 Device Feat	ures		
Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			✓
JTAG BST circuitry			√ (1)
Open-drain output option			✓
Fast input registers		✓	✓
Six global output enables		✓	✓
Two global clocks		✓	✓
Slew-rate control		✓	✓
MultiVolt interface (2)	✓	✓	✓
Programmable register	✓	✓	✓
Parallel expanders	✓	✓	✓
Shared expanders	✓	✓	✓
Power-saving mode	✓	✓	✓
Security bit	✓	✓	✓
PCI-compliant devices available	✓	✓	✓

Notes:

- (1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
- (2) The MultiVolt I/O interface is not available in 44-pin packages.

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

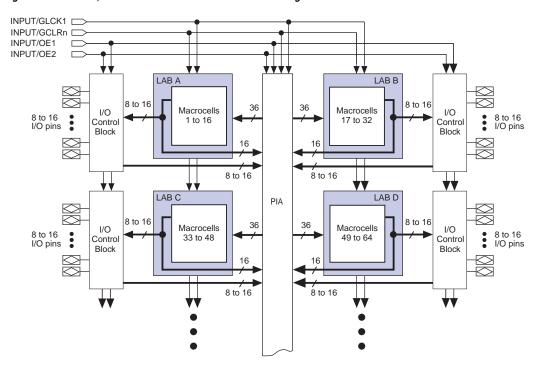


Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

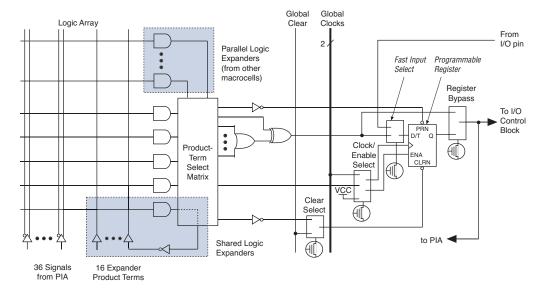
Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

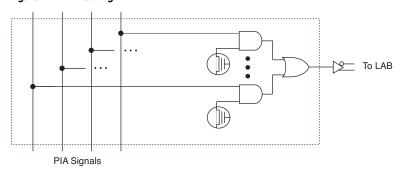
Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell



Programmable Interconnect Array

Logic is routed between LABs via the programmable interconnect array (PIA). This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000 dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 7 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

Figure 7. PIA Routing



While the routing delays of channel-based routing schemes in masked or FPGAs are cumulative, variable, and path-dependent, the MAX 7000 PIA has a fixed delay. The PIA thus eliminates skew between signals and makes timing performance easy to predict.

I/O Control Blocks

The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V_{CC}. Figure 8 shows the I/O control block for the MAX 7000 family. The I/O control block of EPM7032, EPM7064, and EPM7096 devices has two global output enable signals that are driven by two dedicated active-low output enable pins (OE1 and OE2). The I/O control block of MAX 7000E and MAX 7000S devices has six global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When $V_{\rm CCIO}$ is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When $V_{\rm CCIO}$ is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

Programming with External Hardware

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.



For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the *Programming Hardware Manufacturers*.

The instruction register length of MAX 7000S devices is 10 bits. Tables 10 and 11 show the boundary-scan register length and device IDCODE information for MAX 7000S devices.

Table 10. MAX 7000S Boundary-Scan Register Length								
Device	Boundary-Scan Register Length							
EPM7032S	1 (1)							
EPM7064S	1 (1)							
EPM7128S	288							
EPM7160S	312							
EPM7192S	360							
EPM7256S	480							

Note:

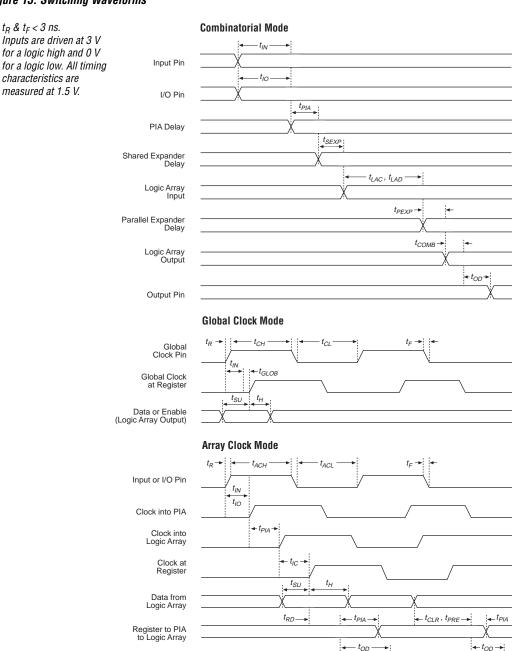
(1) This device does not support JTAG boundary-scan testing. Selecting either the EXTEST or SAMPLE/PRELOAD instruction will select the one-bit bypass register.

Table 11. 32	Table 11. 32-Bit MAX 7000 Device IDCODE Note (1)												
Device		IDCODE (32 B	Bits)										
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)									
EPM7032S	0000	0111 0000 0011 0010	00001101110	1									
EPM7064S	0000	0111 0000 0110 0100	00001101110	1									
EPM7128S	0000	0111 0001 0010 1000	00001101110	1									
EPM7160S	0000	0111 0001 0110 0000	00001101110	1									
EPM7192S	0000	0111 0001 1001 0010	00001101110	1									
EPM7256S	0000	0111 0010 0101 0110	00001101110	1									

Notes:

- (1) The most significant bit (MSB) is on the left.
- (2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

Figure 13. Switching Waveforms



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Register Output to Pin

Tables 19 through 26 show the MAX 7000 and MAX 7000E AC operating conditions.

Symbol	Parameter	Conditions	-6 Speed Grade		-7 Spee	d Grade	Unit
			Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{SU}	Global clock setup time		5.0		6.0		ns
t _H	Global clock hold time		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	2.5		3.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.5		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5	ns
t _{CH}	Global clock high time		2.5		3.0		ns
t _{CL}	Global clock low time		2.5		3.0		ns
t _{ASU}	Array clock setup time		2.5		3.0		ns
t _{AH}	Array clock hold time		2.0		2.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5	ns
t _{ACH}	Array clock high time		3.0		3.0		ns
t _{ACL}	Array clock low time		3.0		3.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	3.0		3.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.6		8.0	ns
f _{CNT}	Maximum internal global clock frequency	(5)	151.5		125.0		MHz
t _{ACNT}	Minimum array clock period			6.6		8.0	ns
f _{ACNT}	Maximum internal array clock frequency	(5)	151.5		125.0		MHz
f _{MAX}	Maximum clock frequency	(6)	200		166.7		MHz

Symbol	Parameter	Conditions	Speed	Grade -6	Speed (Grade -7	Unit
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.4		0.5	ns
t_{IO}	I/O input pad and buffer delay			0.4		0.5	ns
t _{FIN}	Fast input delay	(2)		0.8		1.0	ns
t _{SEXP}	Shared expander delay			3.5		4.0	ns
t_{PEXP}	Parallel expander delay			0.8		0.8	ns
t_{LAD}	Logic array delay			2.0		3.0	ns
t _{LAC}	Logic control array delay			2.0		3.0	ns
t _{IOE}	Internal output enable delay	(2)				2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off, V _{CCIO} = 5.0 V	C1 = 35 pF		2.0		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off, V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.5		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on, V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		7.0		7.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off, V _{CCIO} = 5.0 V	C1 = 35 pF		4.0		4.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off, V _{CCIO} = 3.3 V	C1 = 35 pF (7)		4.5		4.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0	ns
t_{SU}	Register setup time		3.0		3.0		ns
t_H	Register hold time		1.5		2.0		ns
t _{FSU}	Register setup time of fast input	(2)	2.5		3.0		ns
t_{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t_{RD}	Register delay			0.8		1.0	ns
t _{COMB}	Combinatorial delay			0.8		1.0	ns
t _{IC}	Array clock delay			2.5		3.0	ns
t _{EN}	Register enable time			2.0		3.0	ns
t _{GLOB}	Global control delay			0.8		1.0	ns
t _{PRE}	Register preset time			2.0		2.0	ns
t _{CLR}	Register clear time			2.0		2.0	ns
t _{PIA}	PIA delay			0.8		1.0	ns
t_{LPA}	Low-power adder	(8)		10.0		10.0	ns

Table 24	4. MAX 7000 & MAX 7000E Int	ernal Timing Parame	eters Note	e (1)			
Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	OE (-12P)		000 (-12) 00E (-12)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			1.0		2.0	ns
t _{IO}	I/O input pad and buffer delay			1.0		2.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			7.0		7.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.0	ns
t _{LAD}	Logic array delay			7.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.0		3.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		4.0	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.0		7.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		6.0		6.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		7.0		7.0	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0	ns
t _{SU}	Register setup time		1.0		4.0		ns
t _H	Register hold time		6.0		4.0		ns
t _{FSU}	Register setup time of fast input	(2)	4.0		2.0		ns
t _{FH}	Register hold time of fast input	(2)	0.0		2.0		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t _{EN}	Register enable time			7.0		5.0	ns
t _{GLOB}	Global control delay			2.0		0.0	ns
t _{PRE}	Register preset time			4.0		3.0	ns
t _{CLR}	Register clear time			4.0		3.0	ns
t _{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		12.0		12.0	ns

Table 27. EPM7032S External Timing Parameters (Part 2 of 2) Note (1)												
Symbol	Parameter	Conditions				Speed	Grade	!			Unit	
			-	5	-6		-7		-10			
			Min	Max	Min	Max	Min	Max	Min	Max		
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		142.9		116.3		100.0		MHz	
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz	

Table 2	8. EPM7032S Internal Tim	ing Parameter	s /	Note (1)							
Symbol	Parameter	Conditions				Speed	Grade)			Unit
			-5		-6		-7			10	
			Min	Max	Min	Max	Min	Max	Min	Max	-
t _{IN}	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t _{FIN}	Fast input delay			2.2		2.1		2.5		1.0	ns
t _{SEXP}	Shared expander delay			3.1		3.8		4.6		5.0	ns
t _{PEXP}	Parallel expander delay			0.9		1.1		1.4		0.8	ns
t _{LAD}	Logic array delay			2.6		3.3		4.0		5.0	ns
t _{LAC}	Logic control array delay			2.5		3.3		4.0		5.0	ns
t _{IOE}	Internal output enable delay			0.7		0.8		1.0		2.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		0.9		2.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t _{SU}	Register setup time		0.8		1.0		1.3		2.0		ns
t _H	Register hold time		1.7		2.0		2.5		3.0		ns
t _{FSU}	Register setup time of fast input		1.9		1.8		1.7		3.0		ns
t _{FH}	Register hold time of fast input		0.6		0.7		0.8		0.5		ns
t _{RD}	Register delay			1.2		1.6		1.9		2.0	ns
t _{COMB}	Combinatorial delay			0.9		1.1		1.4		2.0	ns
t _{IC}	Array clock delay			2.7		3.4		4.2		5.0	ns
t _{EN}	Register enable time			2.6		3.3		4.0		5.0	ns
t _{GLOB}	Global control delay			1.6		1.4		1.7		1.0	ns
t _{PRE}	Register preset time			2.0		2.4		3.0		3.0	ns
t _{CLR}	Register clear time			2.0		2.4		3.0		3.0	ns

Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	-5		-6		7	-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{FSU}	Register setup time of fast input		1.9		1.8		3.0		3.0		ns
t _{FH}	Register hold time of fast input		0.6		0.7		0.5		0.5		ns
t _{RD}	Register delay			1.2		1.6		1.0		2.0	ns
t _{COMB}	Combinatorial delay			0.9		1.0		1.0		2.0	ns
t _{IC}	Array clock delay			2.7		3.3		3.0		5.0	ns
t _{EN}	Register enable time			2.6		3.2		3.0		5.0	ns
t_{GLOB}	Global control delay			1.6		1.9		1.0		1.0	ns
t_{PRE}	Register preset time			2.0		2.4		2.0		3.0	ns
t _{CLR}	Register clear time			2.0		2.4		2.0		3.0	ns
t _{PIA}	PIA delay	(7)		1.1		1.3		1.0		1.0	ns
t_{LPA}	Low-power adder	(8)		12.0		11.0		10.0		11.0	ns

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 31 and 32 show the EPM7128S AC operating conditions.

Table 3	Table 31. EPM7128S External Timing Parameters Note (1)											
Symbol	Parameter	Conditions	Speed Grade									
			-6		-7		-10		-15		-	
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns	
t _{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns	
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns	
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns	
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns	
t _{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns	
t _{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns	
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns	
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns	
t _{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns	
f _{CNT}	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz	
t _{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns	
f _{ACNT}	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz	
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz	

Table 34. EPM7160S Internal Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-	6	-	7	-1	10	-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns
t _{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns
t _{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns

Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

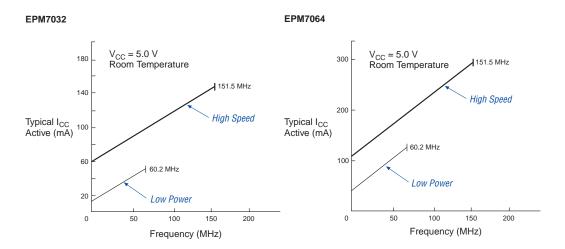
Table 35. EPM7192S External Timing Parameters (Part 1 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-7		-10		-15				
			Min	Max	Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{SU}	Global clock setup time		4.1		7.0		11.0		ns		
t _H	Global clock hold time		0.0		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns		
t _{CH}	Global clock high time		3.0		4.0		5.0		ns		
t _{CL}	Global clock low time		3.0		4.0		5.0		ns		
t _{ASU}	Array clock setup time		1.0		2.0		4.0		ns		

Table 35. EPM7192S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-7		-10		-15				
			Min	Max	Min	Max	Min	Max			
t _{AH}	Array clock hold time		1.8		3.0		4.0		ns		
t _{ACO1}	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns		
t _{ACH}	Array clock high time		3.0		4.0		6.0		ns		
t _{ACL}	Array clock low time		3.0		4.0		6.0		ns		
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns		
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns		
t _{CNT}	Minimum global clock period			8.0		10.0		13.0	ns		
f _{CNT}	Maximum internal global clock frequency	(4)	125.0		100.0		76.9		MHz		
t _{ACNT}	Minimum array clock period			8.0		10.0		13.0	ns		
f _{ACNT}	Maximum internal array clock frequency	(4)	125.0		100.0		76.9		MHz		
f _{MAX}	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz		

Table 36. EPM7192S Internal Timing Parameters (Part 1 of 2) Note (1)										
Symbol	Parameter	Conditions	Speed Grade							
			-7		-10) -15		1	
			Min	Max	Min	Max	Min	Max		
t _{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns	
t _{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns	
t _{FIN}	Fast input delay			3.2		1.0		2.0	ns	
t _{SEXP}	Shared expander delay			4.2		5.0		8.0	ns	
t _{PEXP}	Parallel expander delay			1.2		0.8		1.0	ns	
t_{LAD}	Logic array delay			3.1		5.0		6.0	ns	
t _{LAC}	Logic control array delay			3.1		5.0		6.0	ns	
t _{IOE}	Internal output enable delay			0.9		2.0		3.0	ns	
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns	
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns	
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		7.0	ns	
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns	
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns	
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns	
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns	
t _{SU}	Register setup time		1.1		2.0		4.0		ns	

Figure 14 shows typical supply current versus frequency for MAX 7000 devices.

Figure 14. I_{CC} vs. Frequency for MAX 7000 Devices (Part 1 of 2)



EPM7096

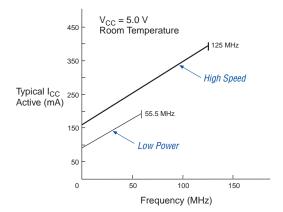
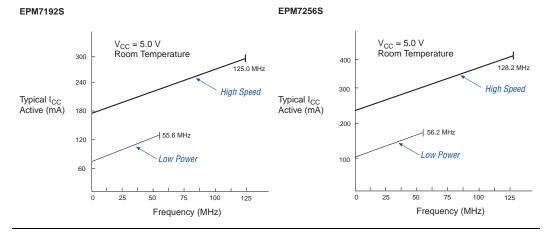


Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 2 of 2)



Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

Figure 21. 192-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

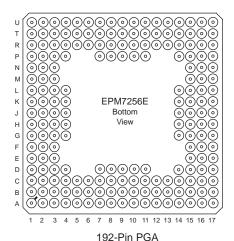


Figure 22. 208-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

